

COLLECTION OF CTL DECISIONS

Decision

Standard: IEC 60950, 2 nd and 3 rd Ed.	Sub clause: 2.9.3, Table 6, condition 3	Sheet n. 380 Page 1 (1)
Subject: Affect of solder resist on Comparative Tracking Index (CTI) of Printed Wiring Boards	Key words: -comparative tracking index -CTI -printed wiring boards -PWB -solder resist	Decision confirmed at CTL 38th meeting
Question: The measured Comparative Tracking Index (CTI) for a printed wiring board with solder resist present can be different than that for the printed wiring board without the solder resist. The creepage distances required in the standard depends upon the CTI for the printed wiring board. Should the presence of solder resist on a printed wiring board be considered in determining the CTI when determining the creepage distances requirements to be applied? <i>Note – Clause 2.9.5 does not apply to this question because the assembled printed wiring board is not covered with a conformal coating.</i> Decision: Yes. Explanatory notes: --		